

DERWENT-ACC-NO: 1997-454139

DERWENT-WEEK: 199742

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TITLE: Hot-melt adhesive for bonding paper - contains  
hollow microsphere filler which does not soften at the  
melting point of the adhesive

PATENT-ASSIGNEE: SEKISUI CHEM IND CO LTD[SEKI]

PRIORITY-DATA: 1996JP-0015269 (January 31, 1996)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE
PAGES MAIN-IPC		
JP 09208913 A	August 12, 1997	N/A
004 C09J 011/04		

APPLICATION-DATA:

PUB-NO	APPL-DESCRIPTOR	APPL-NO
APPL-DATE		
JP 09208913A	N/A	1996JP-0015269
January 31, 1996		

INT-CL (IPC): C09J011/04, C09J011/08

ABSTRACTED-PUB-NO: JP 09208913A

BASIC-ABSTRACT:

Adhesive (P) consists of hot-melt adhesive (A) and hollow microsphere filler

(B), which does not soften at the m. pt. of (A) and has a true specific gravity of 0.1-0.9 and has a density at 20 deg. C of 0.96-0.80 g/cm3.

USE - (P) is suitable for bonding paper.

ADVANTAGE - (P) can be easily and efficiently separated from pulp in the process for repulping of waste paper.

CHOSEN-DRAWING: Dwg.0/0

TITLE-TERMS: HOT MELT ADHESIVE BOND PAPER CONTAIN HOLLOW MICROSPHERE  
FILL

SOFTEN MELT POINT ADHESIVE

DERWENT-CLASS: A81 G03

CPI-CODES: A08-R01; A12-A05; G03-B01; G03-B02;

ENHANCED-POLYMER-INDEXING:

Polymer Index [1.1]

018 ; P0000

Polymer Index [1.2]

018 ; ND01 ; ND04 ; Q9999 Q6666 Q6644 ; K9449 ; N9999 N5721\*R ;  
K9676\*R ; K9563 K9483 ; Q9999 Q9154 ; B9999 B5607 B5572 ; B9999  
B4831\*R B4740

Polymer Index [1.3]

018 ; D00 ; G2880 D00 Si 4A ; A999 A237 ; S9999 S1398 ; A999 A771  
; B9999 B4831\*R B4740 ; B9999 B5209 B5185 B4740 ; B9999 B5629

B5572

Polymer Index [1.4]

018 ; D00 ; G3098 D00 F20 O\* 6A Si 4A ; A999 A237 ; S9999 S1398  
; A999 A771 ; B9999 B4831\*R B4740 ; B9999 B5209 B5185 B4740 ;

B9999

B5629 B5572

Polymer Index [1.5]

018 ; D01 ; A999 A237 ; A999 A771 ; S9999 S1398 ; B9999 B4831\*R  
B4740 ; B9999 B5209 B5185 B4740 ; B9999 B5629 B5572

Polymer Index [2.1]

018 ; P0464\*R D01 D22 D42 F47 ; S9999 S1398 ; A999 A237 ; A999

A782

Polymer Index [2.2]

018 ; P0226 P0282\*R D01 D18 F30 ; S9999 S1398 ; A999 A237 ; A999  
A782

Polymer Index [2.3]

018 ; R00708 G0102 G0022 D01 D02 D12 D10 D19 D18 D31 D51 D53 D58  
D76 D88 ; H0000 ; S9999 S1398 ; A999 A237 ; A999 A782 ; P1741 ;  
P1752

Polymer Index [2.4]

018 ; B9999 B5209 B5185 B4740 ; B9999 B4831\*R B4740 ; B9999 B5629  
B5572

SECONDARY-ACC-NO:

CPI Secondary Accession Numbers:

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